



EKC220™

EKC PlasmaSolv® Line - HDA™ Technology

Product Description

EKC220™ is an aqueous organic mixture formulated to remove post-etch residues after via and metal processes.

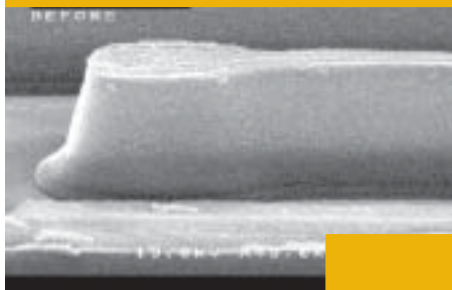
Applications

This product is similar to EKC265™ but utilizes hydroxylamine more efficiently as a result of product optimization. Originally developed to address Ti undercut with a cost effective formulation.

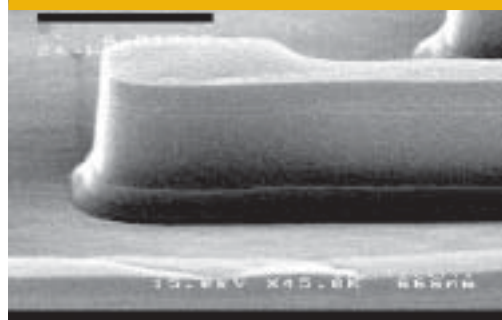
Product Performance

- Removes residues after metal or via etch processes - lowers via contact resistance.
- Compatible with automatic equipment
- Does not require ultrasonics
- Maintains gate oxide integrity
- Improves contact between metal layers

After Etch & Ash



*After EKC220™
(65°C/20 min/IPA/H₂O)*



Metal	Etch rate (Å/min)	Visual Inspection
Al (0.5% Cu)	1.6	Good
W	2.6	Good
Ti	0	Good

Experimental Conditions

70°C 30 min/IPAJ H₂O/N₂ dry

Measurement: 4-point probe

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